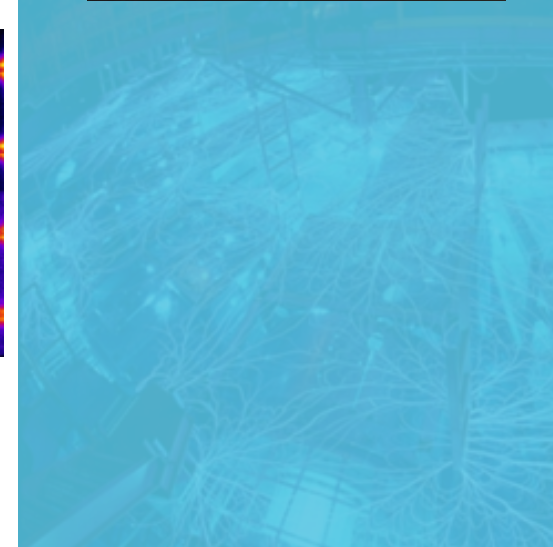
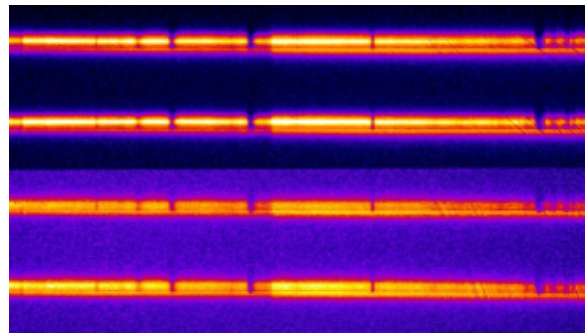
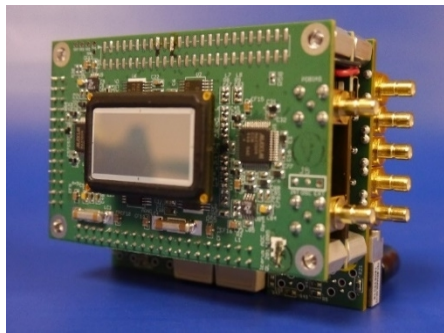
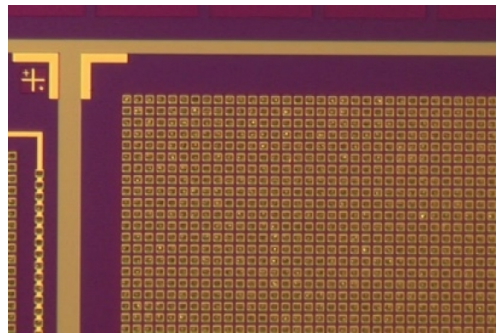
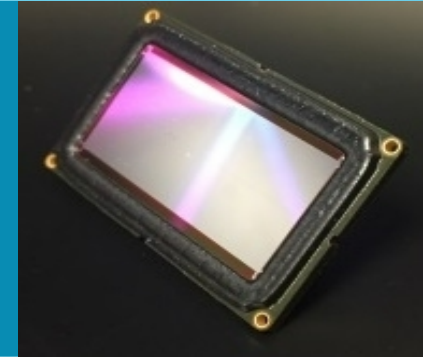




UXI/hCMOS development and deployment at Sandia National Laboratories



PRESENTED BY

Anthony “Tony” Colombo

On behalf of the Sandia UXI/hCMOS effort

2021 National Diagnostic Workshop, 8 December
2021



Many people have contributed to the UXI/hCMOS effort at Sandia in recent years.



hCMOS design, fabrication, packaging

- Liam Claus
- Eric Edwards
- Troy England
- Lu Fang
- Patrick Finnegan
- Tom Hill
- Tim McArdle
- Brandon Mitchell
- Andy Montoya
- Eric Morgan
- Doug Nichols
- Gideon Robertson
- Marcos Sanchez
- Andrew Starbuck
- Michael Wood

UXI-at-Z development and deployment

- Tony Colombo
- Aaron Edens
- Mark Kimmel
- Joel Long
- Quinn Looker
- John Porter
- Robert Speas
- John Stahoviak

Programmatic support

- Michael Jones
- Greg Rochau

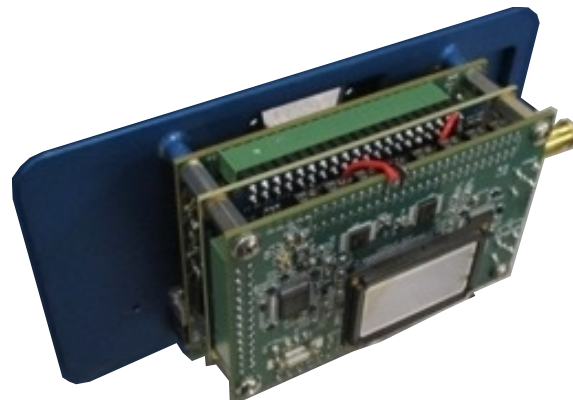
Engineering and fielding support

- Greg Dunham
- Dan Folker
- Eric Harding
- Robert Hohlfelder
- Paul Gard
- Jeff Kellogg
- Brian Ritter
- Katie Seals
- Shane Speas

UXI/hCMOS makes nanosecond-gate, burst-mode, framing cameras.



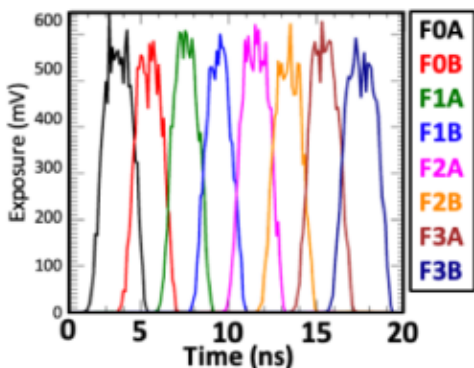
UXI camera with Icarus hCMOS sensor.



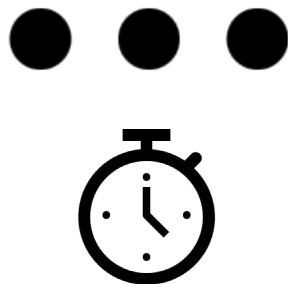
Framing cameras capture a full, 2D image.

- Only one imaging line of sight.
- All pixels image at (approximately) the same time.

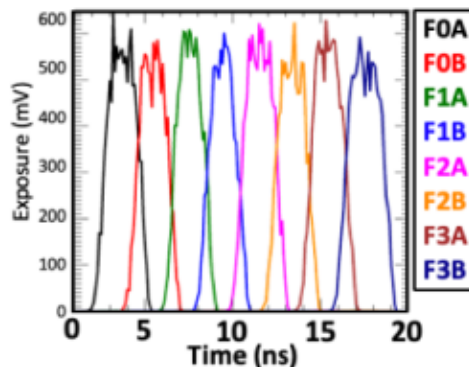
Acquire several frames in a short burst.



Wait many milliseconds.



Acquire another burst of frames.



4 ns
frame-to-frame

UXI camera is ultrafast for a (very) short duration.



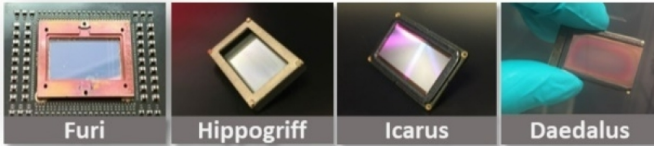
Well matched to single-shot HEDP experiments.

UXI cameras can detect both x-rays and visible photons.

Many parts come together to make a hybrid CMOS UXI camera.

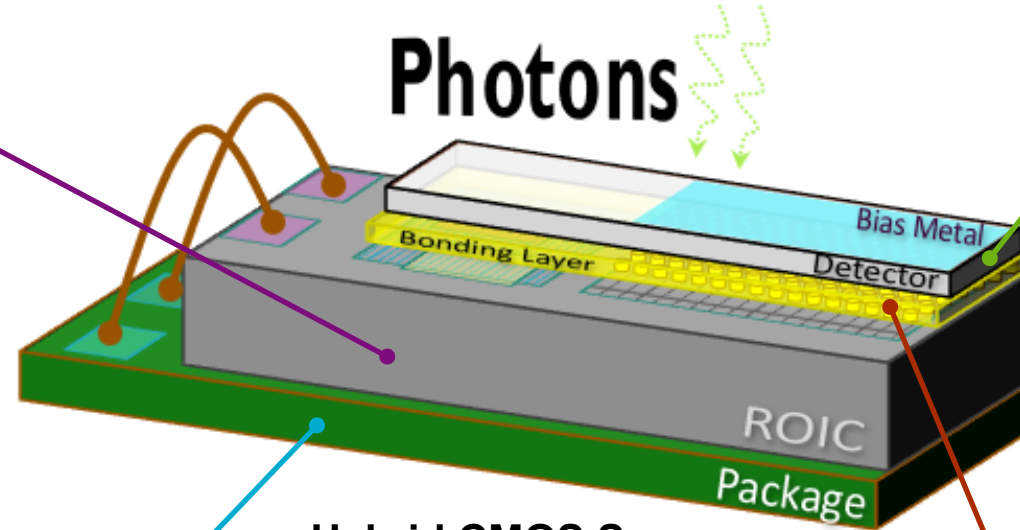


Readout Integrated Circuit



- Fabricated in SNL's 350-nm CMOS
- 1-2 ns minimum shutter time, 2-8 frames
- 1024x512 array of 25 μm x 25 μm pixels
- Adjustable shutter timing

Package

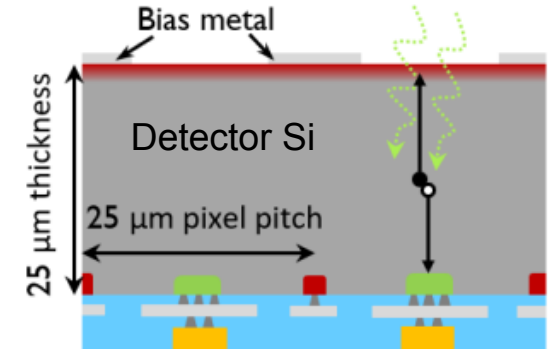


Hybrid CMOS Sensor



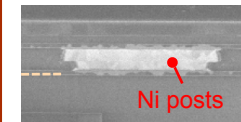
UXI Camera System Development for Application-Specific Needs

Detector Array

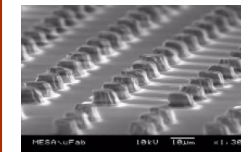


Integration

Direct Bond Interconnect (DBI)



- External supplier
- Wafer-to-wafer bond



Indium bump

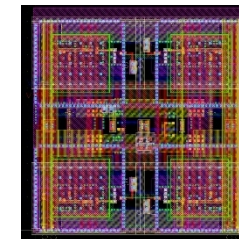
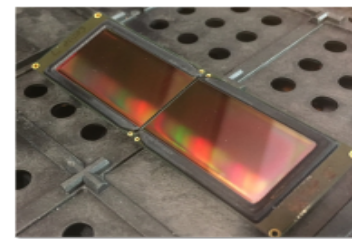
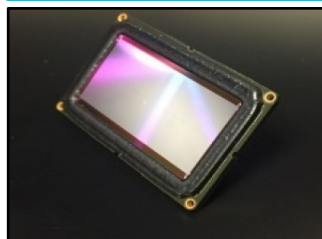
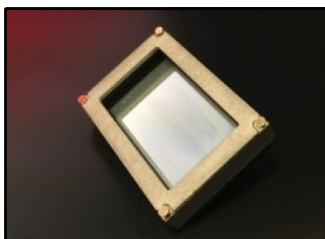
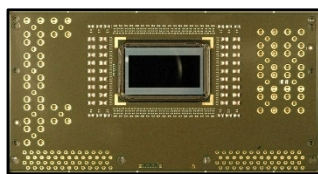
- Processing at Sandia
- Die-level processing

Icarus is the currently deployed sensor in an advancing hCMOS product line.

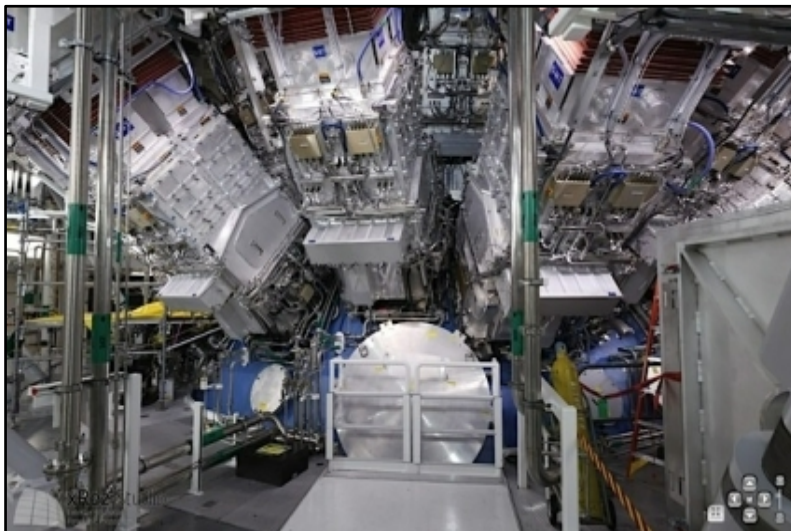


	Retired		Deployed
	Furi	Hippogriff	Icarus V1/V2
Year	FY14	FY15	FY16-18
Minimum Gate Time	~1.5 ns	~2 ns	~1.5 ns
Frames	2 (full resolution)	2 (full resolution) 4 or 8 (Row interlaced)	4 (full resolution) 8 (L/R interlaced)
Tiling Option	No	No	No
CMOS Process	350 nm (SNL)	350 nm (SNL)	350 nm (SNL)
Pixels	448 × 1024	448 × 1024	512 × 1024
Pixel Size	25 μm × 25 μm	25 μm × 25 μm	25 μm × 25 μm
Capacitor Full Well	1.5 million e ⁻	1.5 million e ⁻	0.5 million e ⁻

In Test	In Production
Daedalus V1/V2	Tantalus
FY19-22	FY23
~1.0 ns	~0.5 ns
3 (full resolution) 6+ (Row/L/R interlaced)	4 (full resolution) 16+ (Row/quadr. interlaced)
One Side	No
350 nm (SNL)	130 nm (Tower Jazz)
512 × 1024	512 × 1024
25 μm × 25 μm	25 μm × 25 μm
1.5 million e ⁻	0.5 million e ⁻



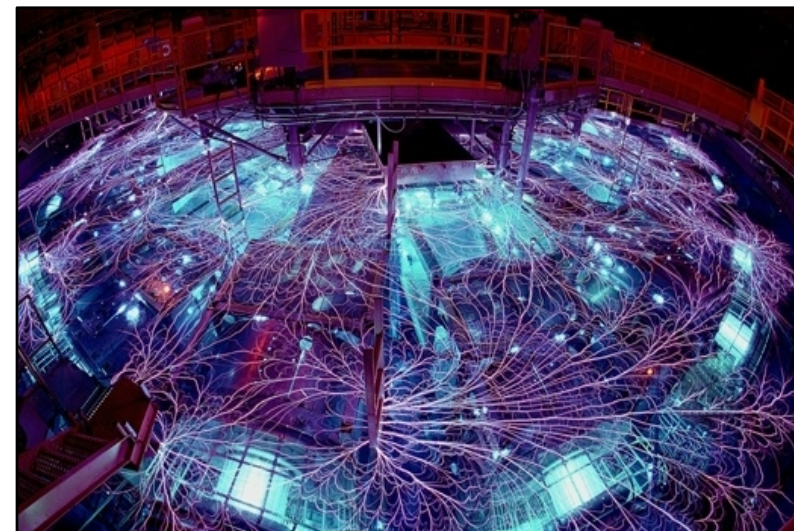
UXI cameras have been deployed in time-resolved diagnostics across multiple facilities.



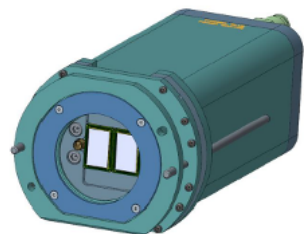
National Ignition Facility



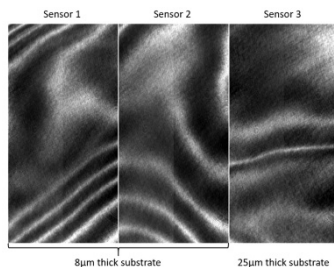
Omega



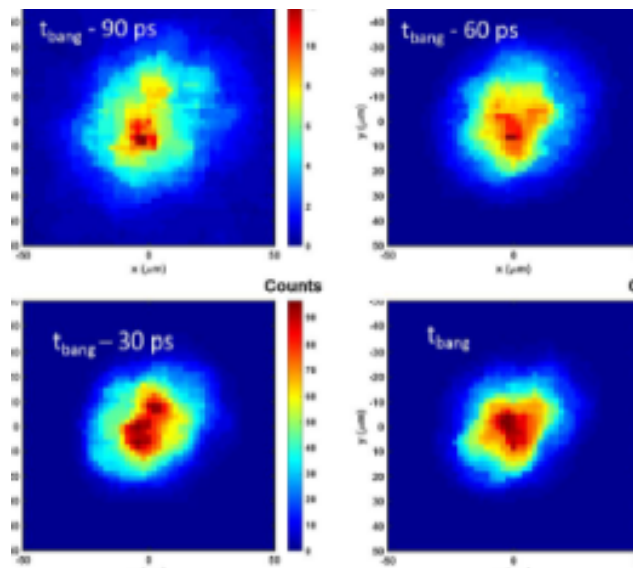
Z-Machine



GLEH2

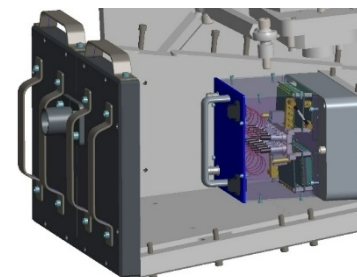
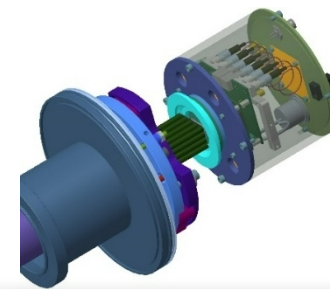


TRNF

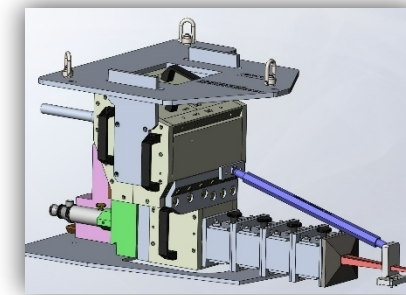


SLOS-TRXI

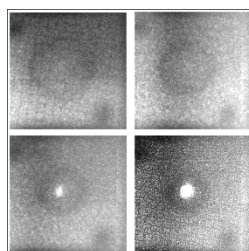
FOA Pinhole Camera



Gated Backlighting



MONSSTR

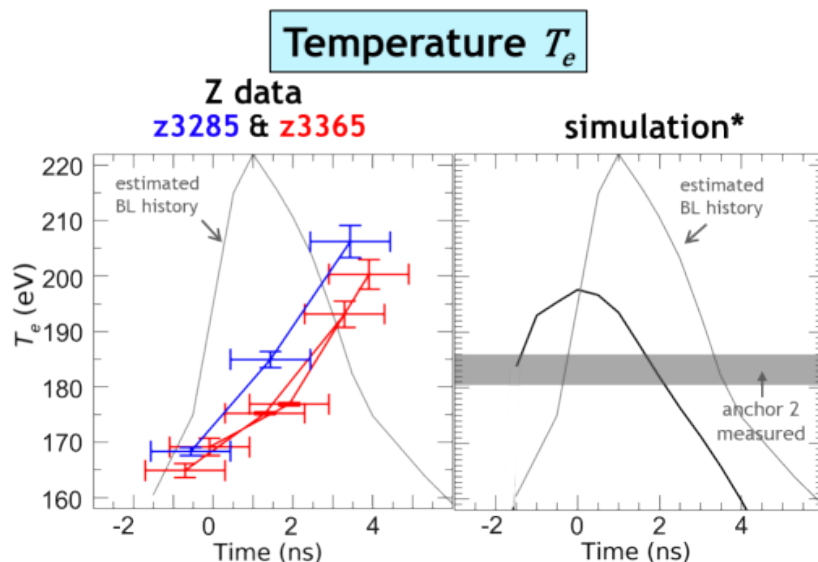
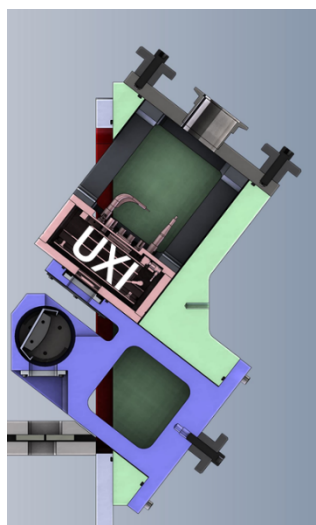


SLOS1-CBI

UXI cameras provide better data and qualitative insights across multiple diagnostics.

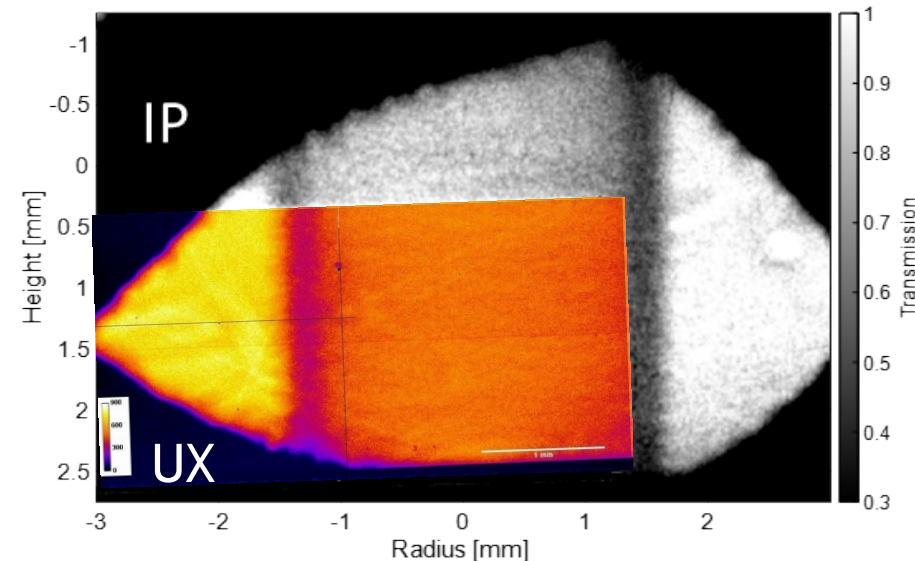


Opacity Spectrometer: Fe condition evolution trends qualitatively disagree with predictions.

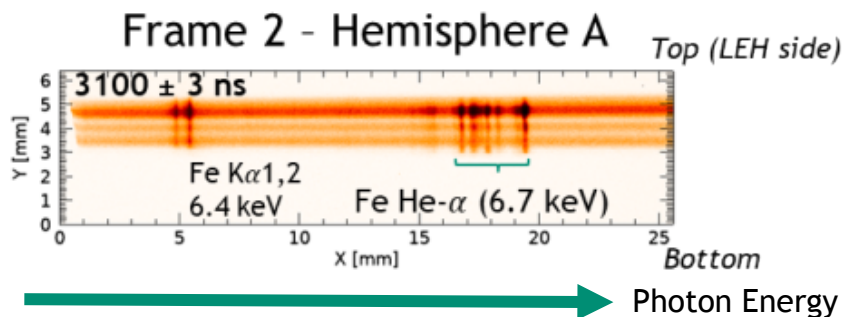


Analyzed data courtesy of Guillaume Loisel. *Simulations: Nagayama et al., *PRE* 93, 023202 (2016).

Gated crystal backlighting: Contrast with UXI is superior to image plate.



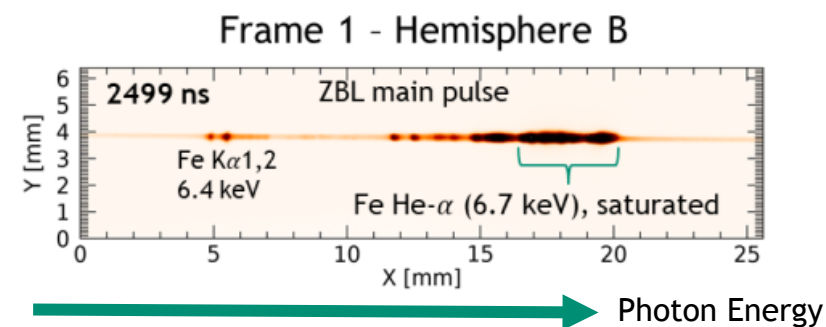
Processed image plate data courtesy of David Yager-Elorriaga.



Time-resolved Fe spectrum of a MagLIF target at stagnation.

The MONSSTR records time-resolved x-ray spectra of targets in the Z chamber.

MONSSTR data analysis courtesy of Eric Harding.



X-ray spectra generated by ZBL striking an Fe backlighter foil.

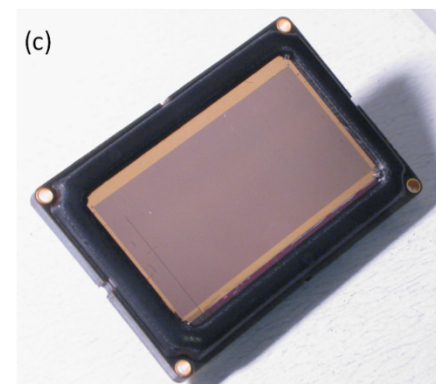
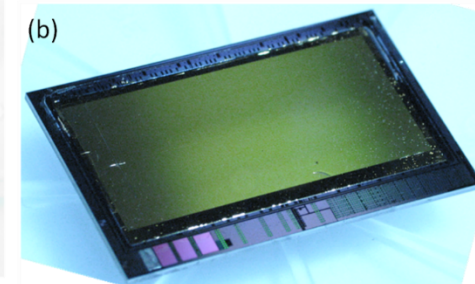
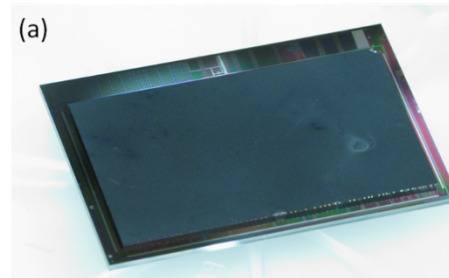
Upgrades such as tiled Daedalus and GaAs detector arrays are in the works.



Notable Daedalus Features

- 1-ns gates.
- Row-wise interlacing.
- $3 \times$ deeper full well than Icarus.

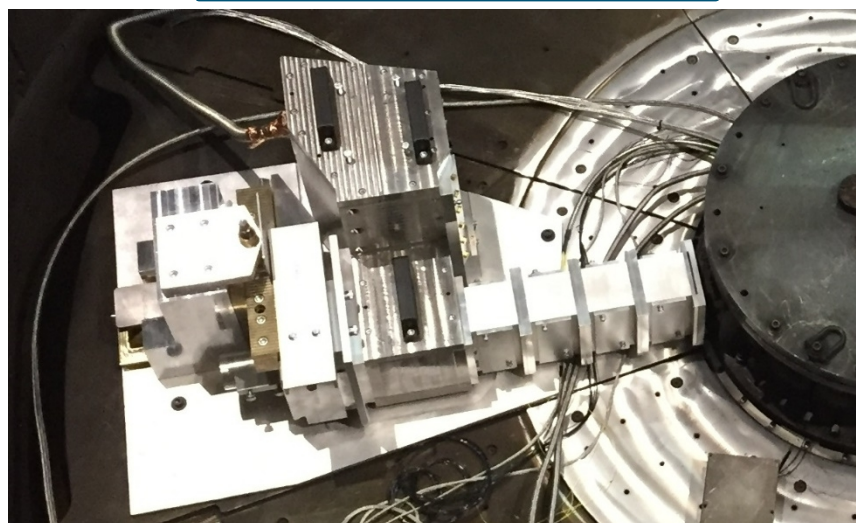
Packaged Daedalus V2 sensors are expected in FY 2022.



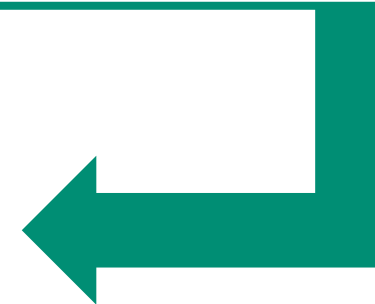
GaAs-hybridized Icarus sensors are expected in FY 2022.

**MONSSTR
spectrometer**

Daedalus abuts on the short side for more spectral coverage.



GaAs detector arrays will be effective to 40 - 50 keV.



9 Other high-speed, solid-state electronic detectors are also in development at Sandia.



UPAC Key Specifications

Number of Channels : 32

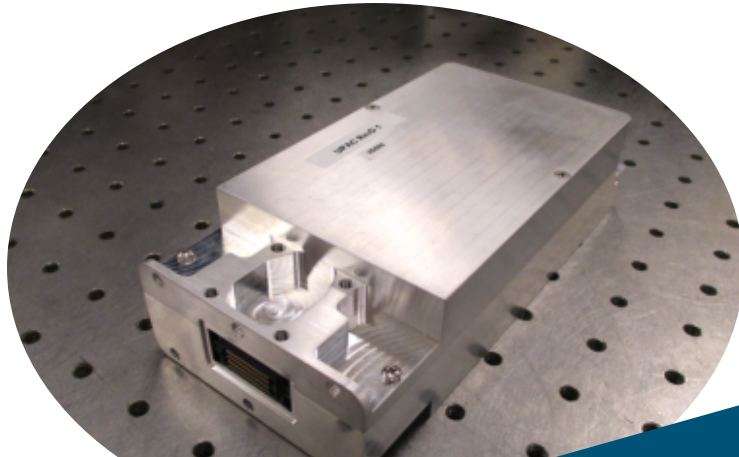
Sample Rate : 9.2 GS/s

Record Length : 114 ns

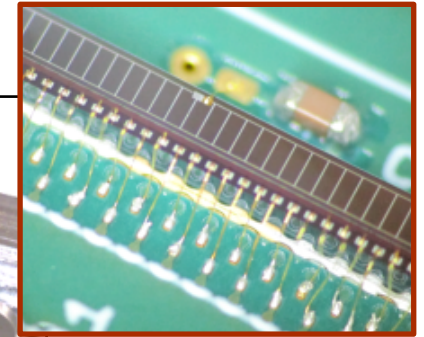
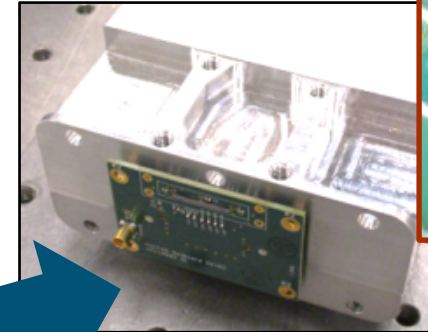
Analog Bandwidth : 1.9 GHz

Voltage Range : 0.1 – 1.1 V

Ultrafast Pixel Array Camera (UPAC)

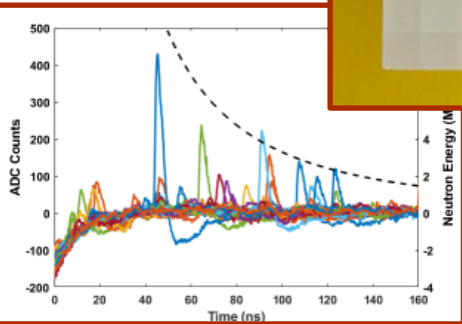
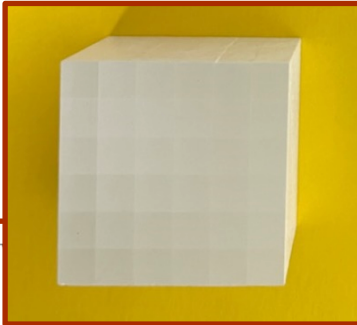


1D Photodiode Array

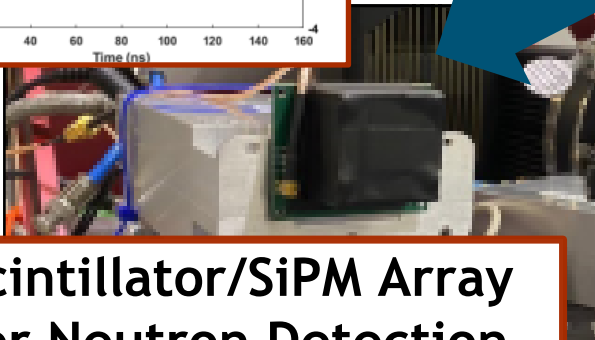


Slated for deployment on Z in March 2022 to measure x-rays.

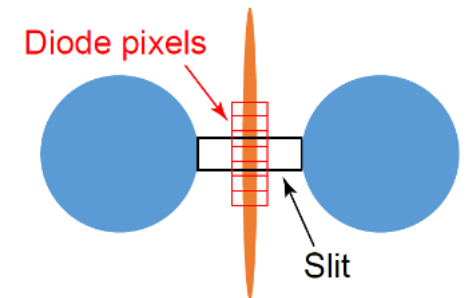
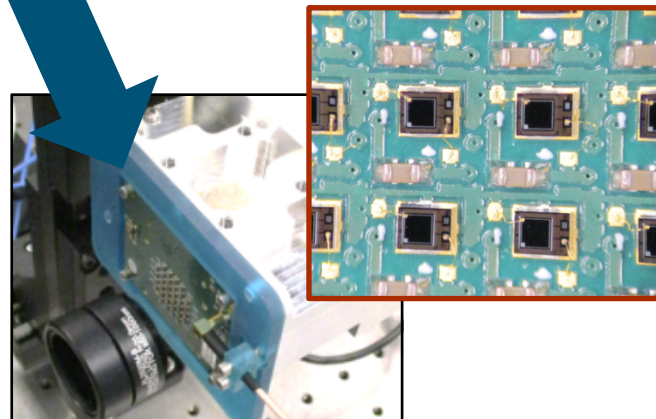
Application-Specific Interface Cards



Scintillator/SiPM Array for Neutron Detection



2D Photodiode Imaging Array



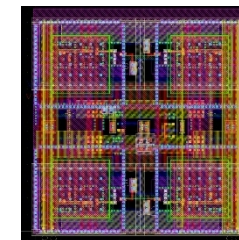
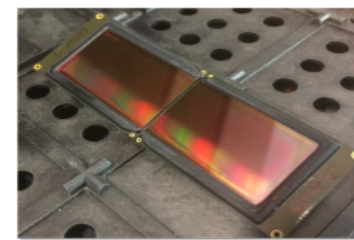
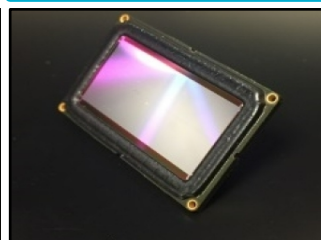
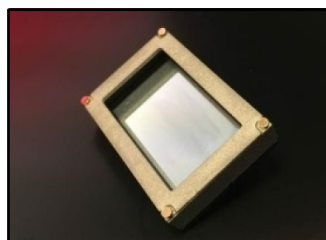
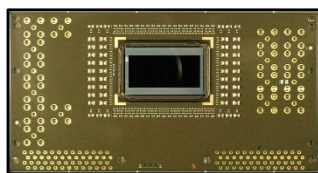
Magnetically Ablated Reconnection on Z (MARZ) platform.
Image courtesy of Clayton Myers.

Icarus is the currently deployed sensor in an advancing hCMOS product line.



	Retired		Deployed
	Furi	Hippogriff	Icarus V1/V2
Year	FY14	FY15	FY16-18
Minimum Gate Time	~1.5 ns	~2 ns	~1.5 ns
Frames	2 (full resolution)	2 (full resolution) 4 or 8 (Row interlaced)	4 (full resolution) 8 (L/R interlaced)
Tiling Option	No	No	No
CMOS Process	350 nm (SNL)	350 nm (SNL)	350 nm (SNL)
Pixels	448 × 1024	448 × 1024	512 × 1024
Pixel Size	25 μm × 25 μm	25 μm × 25 μm	25 μm × 25 μm
Capacitor Full Well	1.5 million e ⁻	1.5 million e ⁻	0.5 million e ⁻

In Test	In Production
Daedalus V1/V2	Tantalus
FY19-22	FY23
~1.0 ns	~0.5 ns
3 (full resolution) 6+ (Row/L/R interlaced)	4 (full resolution) 16+ (Row/quadr. interlaced)
One Side	No
350 nm (SNL)	130 nm (Tower Jazz)
512 × 1024	512 × 1024
25 μm × 25 μm	25 μm × 25 μm
1.5 million e ⁻	0.5 million e ⁻





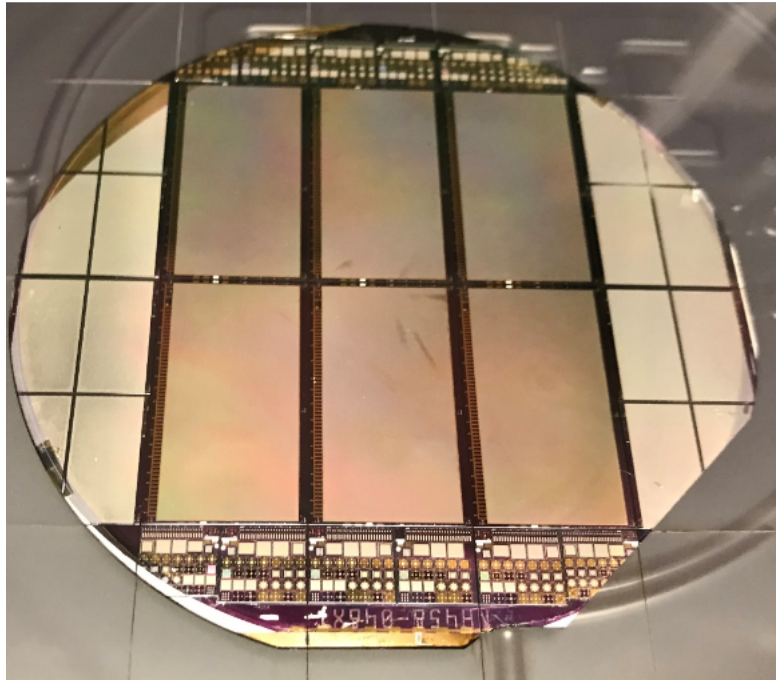
Tentative Daedalus V2 production schedule: First sensors available in June 2022.



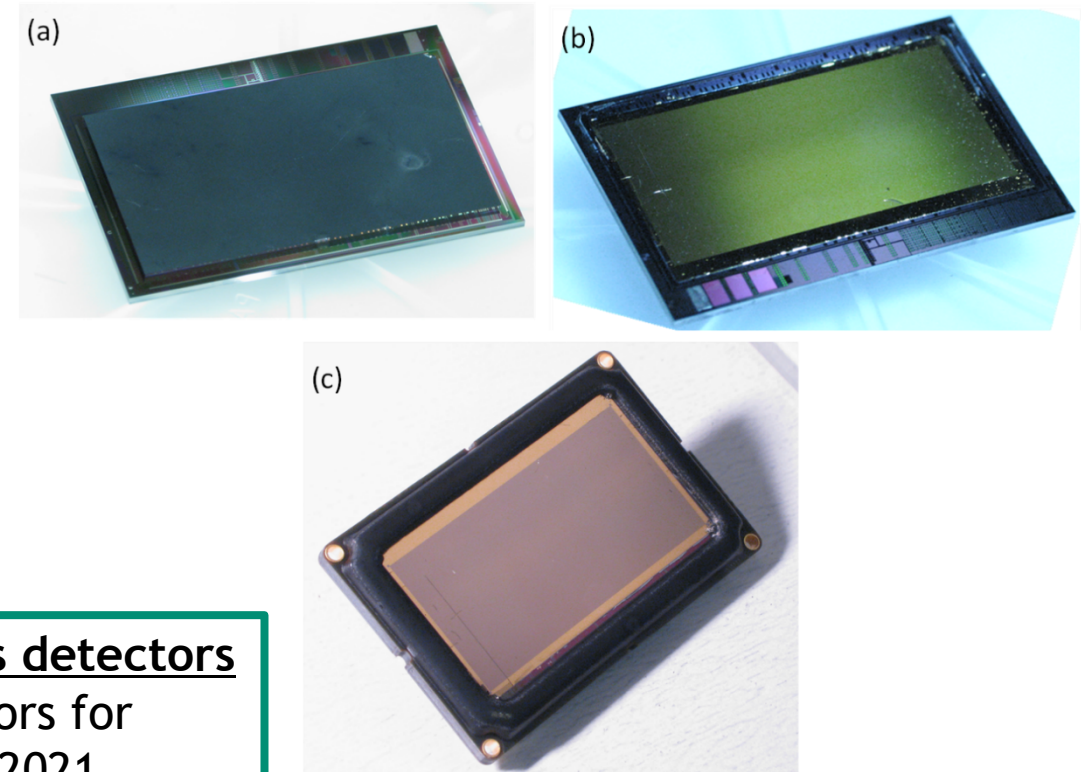
ROIC	Wafer	Hybridization	FY22												FY23												Estimated Available Sensors				
			Q1			Q2			Q3			Q4			Q1			Q2			Q3			Q4							
			O	N	D	J	F	M	A	M	J	J	A	S	O	N	D	J	F	M	A	M	J	J	A	S	A+	A/A-	B's	C's	Lower
DV2	2021:1	25umSi			H		T		P	T	A															5	7	1	2	3	
	2021:2	25umSi			H		T			P	T	A													5	7	1	2	3		
	2021:3	25umSi			H		T				P	T	A											5	7	1	2	3			
	2021:4	25umSi			H		T					P	T	A										5	7	1	2	3			
	2021:5	25umSi			H		T						P	T	A									5	7	1	2	3			
	2021:6	25umSi			H		T							P	T	A								5	7	1	2	3			
	2021:7	TBD															H		P	T	A			5	7	1	2	3			
	2021:8	TBD															H			P	T	A		5	7	1	2	3			
	2021:9	TBD															H				P	T	A	5	7	1	2	3			
	2021:10	TBD															H					P	T	A	5	7	1	2	3		
	2021:E1	NA																							0	0	0	0	0		
	2021:E2	NA																							0	0	0	0	0		

	F	Fabrication	H	Hybridization	P	Packaging	T	Testing	A	Available	50	70	10	20	30
--	---	-------------	---	---------------	---	-----------	---	---------	---	-----------	----	----	----	----	----

The first GaAs-hybridized Icarus sensors are expected in early 2022.



3"-diameter wafer containing 6 GaAs detector arrays.

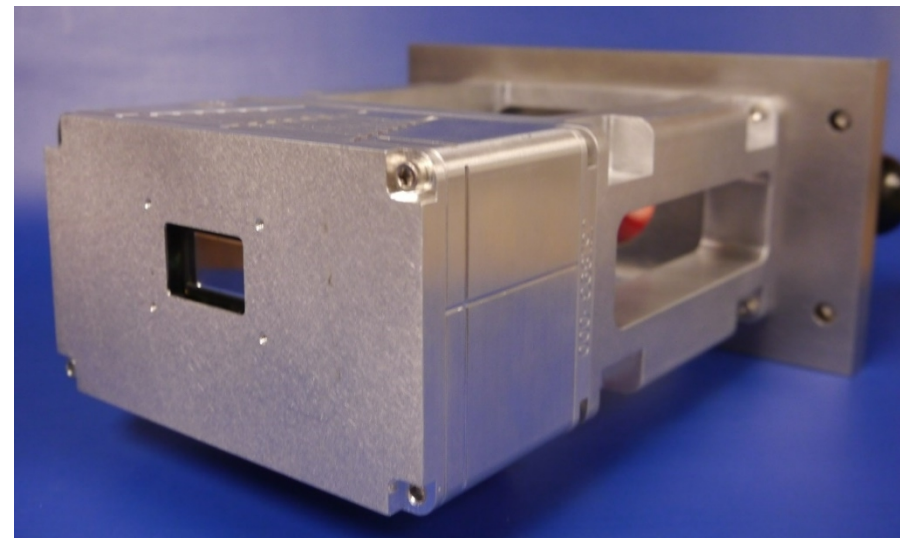
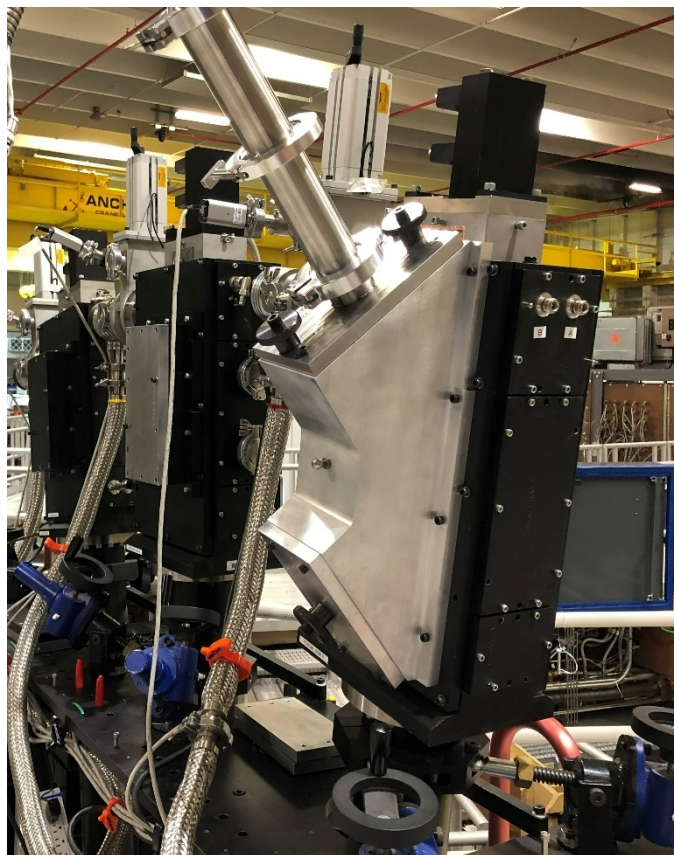
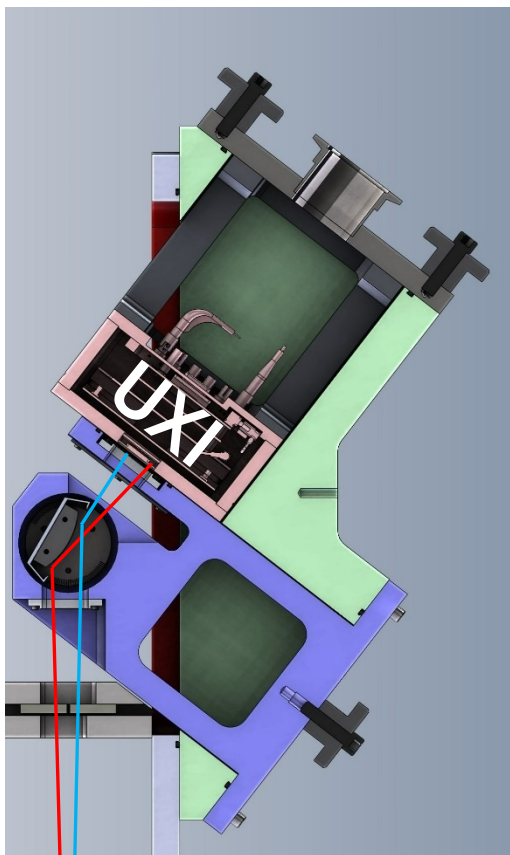


Deployment Plan for GaAs detectors

- Send 6 GaAs Icarus sensors for packaging in December 2021.
- Test these Icarus devices and report status to the community before the end of FY 2022.
- If successful, adapt the design to Daedalus. Potential availability in FY 2023.

- a) After flip-chip bonding.
- b) After substrate remove and backside metallization.
- c) After final packaging onto an Icarus read-out PCB.

At Z, the convex crystal spectrometer is used to measure sample conditions and opacities.



Benefits of time-resolving

- Measure multiple different sample conditions per shot...
- ...instead of integrating over them.
- Evaluate sample evolution models.
- Assess hypotheses about discrepancies between models and data.
- Gate out time-integrated background.

----- Imaging slits

— FeMg opacity sample



X-ray source
4 m from spectrometer

Spectrometer: Bailey et al, *RSI* **79**, 113104 (2008).
Opacities, e.g.: Bailey et al, *Nature* **517**, 56-59 (2015).

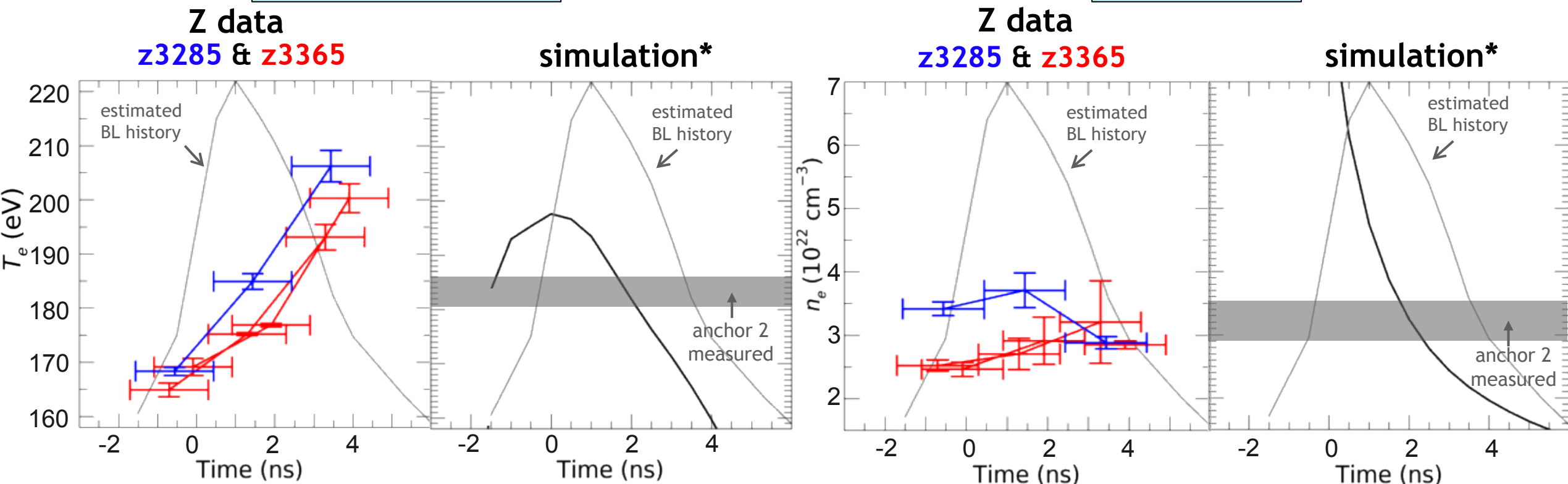
Time-resolved results are challenging the understanding of this experimental platform.



Temperature T_e

Fe condition evolution trends disagree with simulation predictions.

Density n_e



“Anchor 2” ~ Solar

$$T_e = 182 \text{ eV}, n_e = 3.1 \times 10^{22} \text{ cm}^{-3}$$

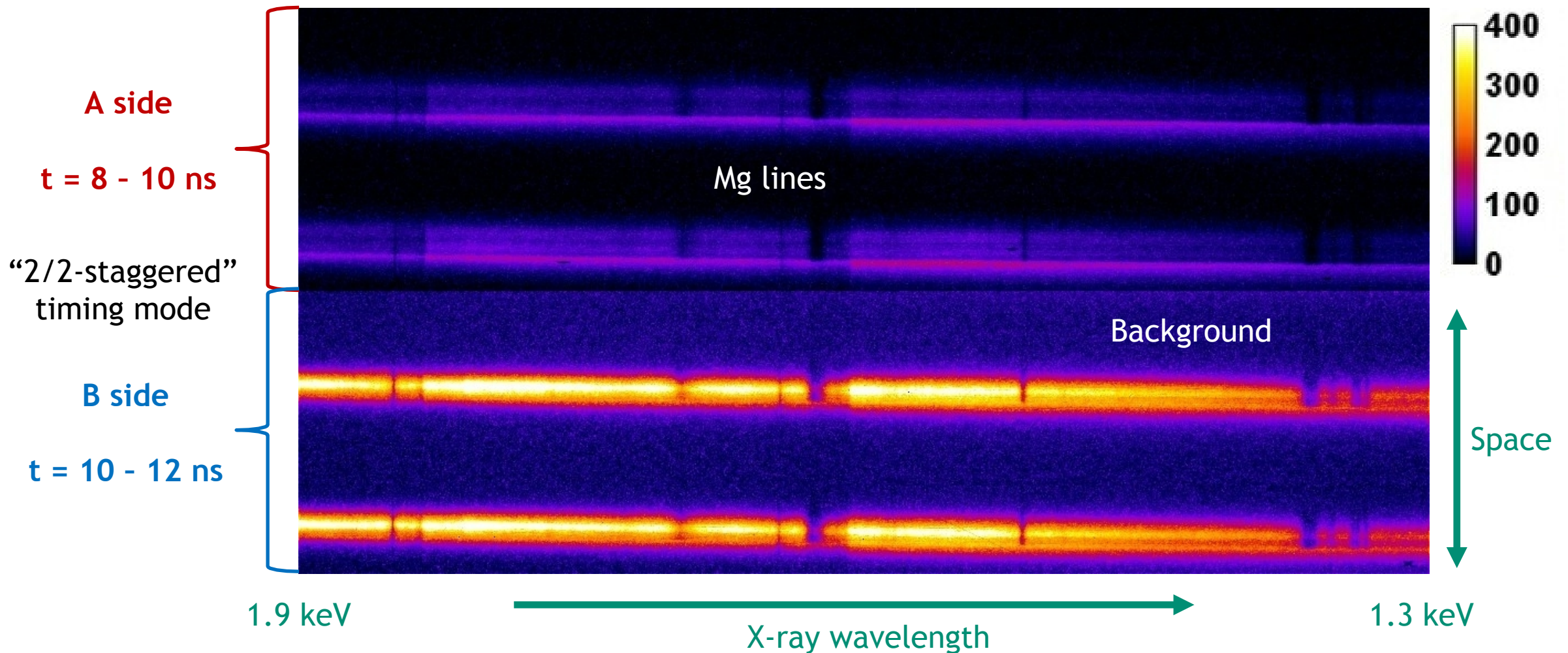
Analyzed data courtesy of
Guillaume Loisel.

*Simulations: Nagayama et al., *PRE* 93, 023202 (2016).

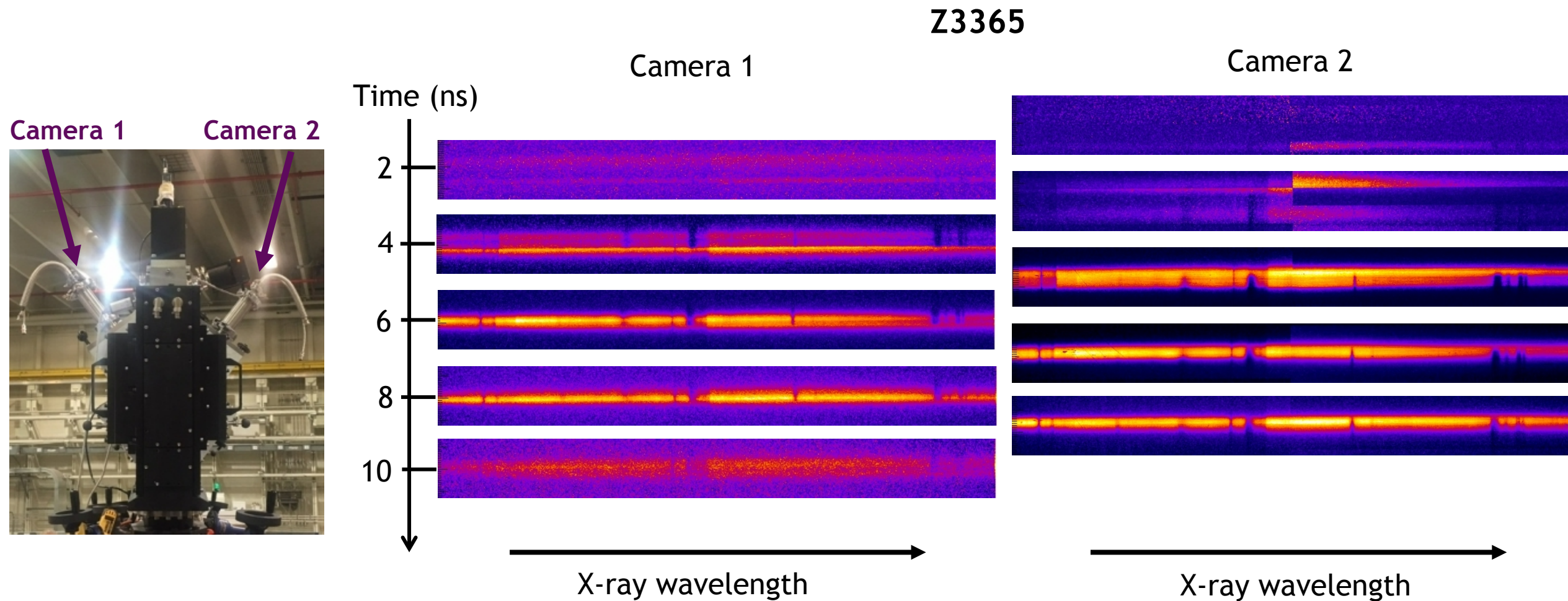
In some applications, each camera frame can capture two different exposures without dead time.



Opacity Spectrometer in the Axial Package Z3365 Camera 1, 3rd Frame (of 4)



Using 2 cameras in the Axial Package, we routinely collect 10+ exposures per Z shot.



Use-inspired characterization of diagnostics is crucial because illumination can have nonlocal effects on the sensor.

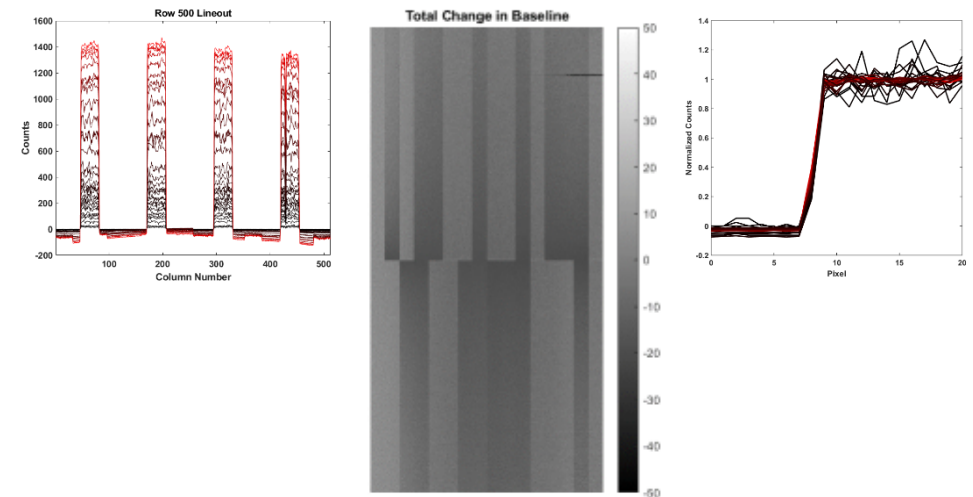
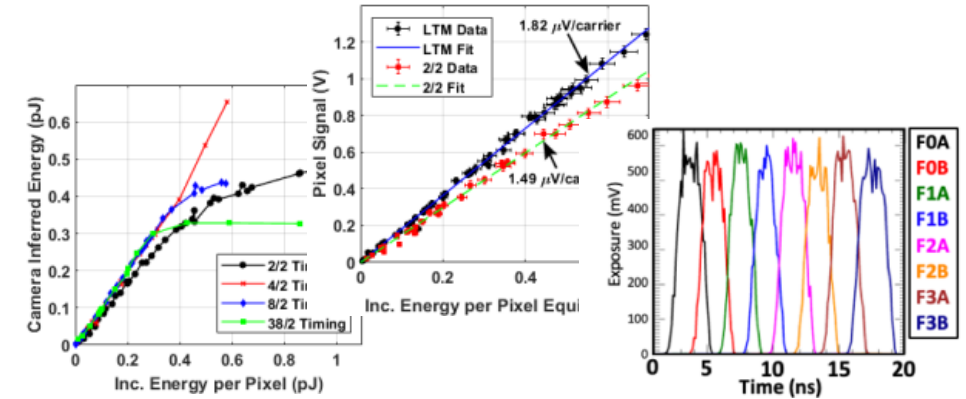


Example requirements from end-user

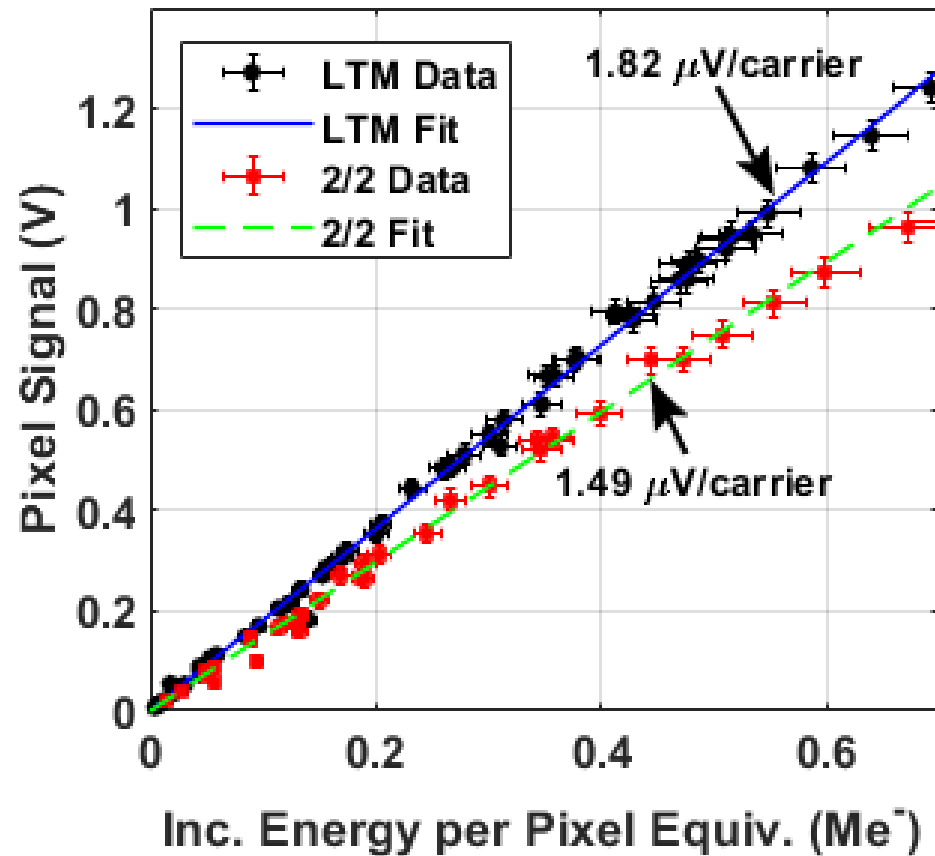
- Accurate Mg line transmission measurement:
 - High S/N spectra.
 - Linear photon response.
 - Sufficient spectral resolution.
 - Avoid feature saturation.
 - Reproducibility.
- Multiple timesteps to truly observe evolution.



Calibrated x-ray, optical, fabrication, and temporal characterizations.



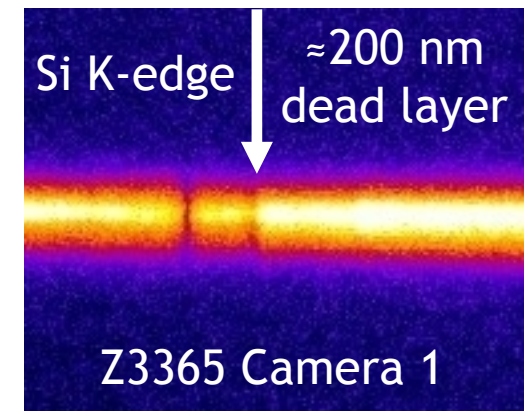
The parameters for absolute UXI camera sensitivity have been measured.



2/2 timing sensitivity is different from other modes!

Linearity is good through maximum spectrometer signal.

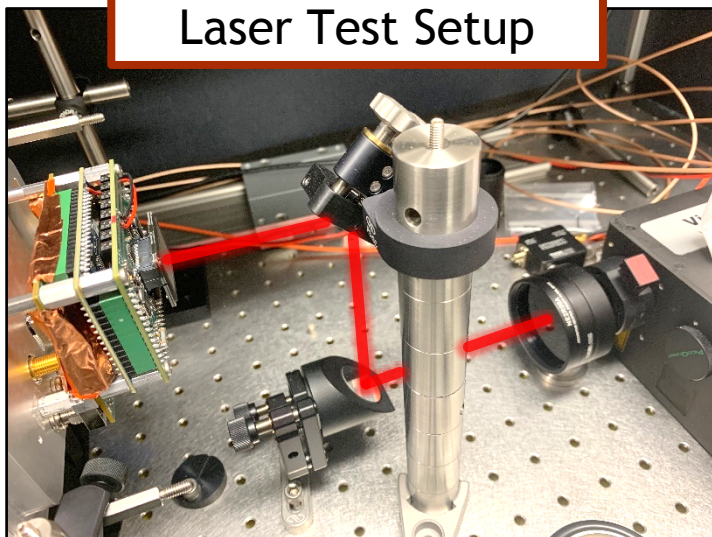
Shot data is consistent with fab spec of dead layer thicknesses.



Detector is 25 μm thick Si.

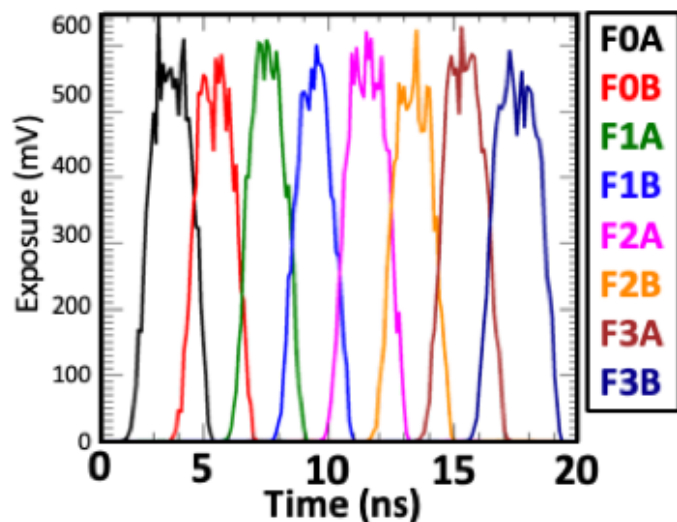
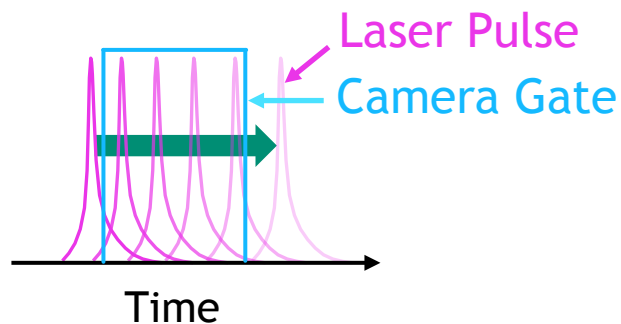
Total camera response

We do a bevy of other camera tests and characterizations to qualify diagnostics for deployment in Z.

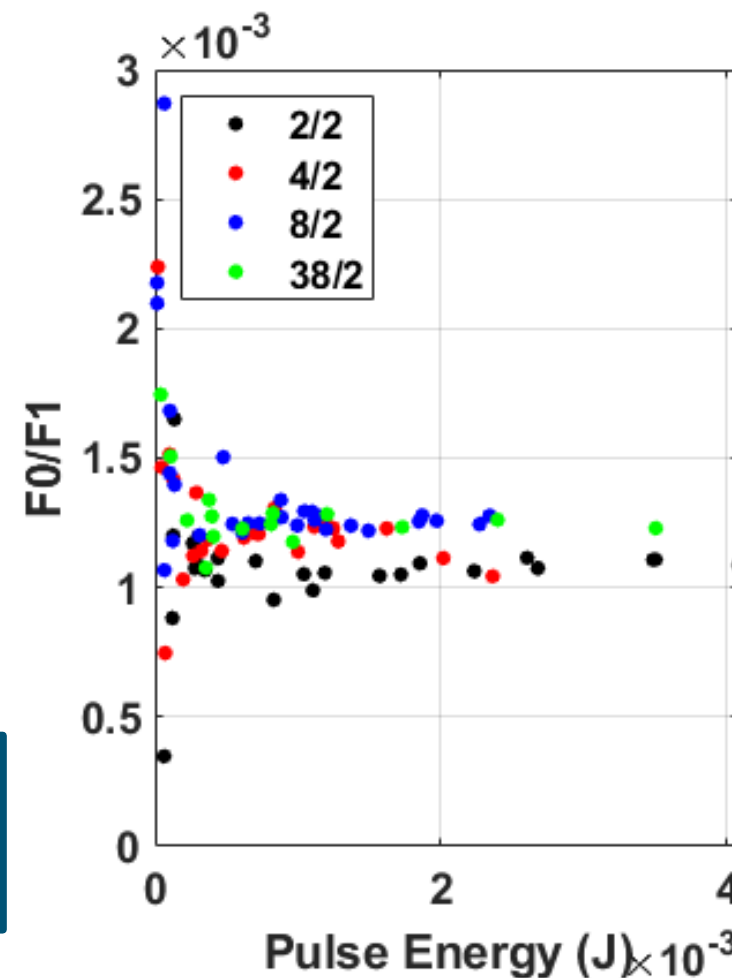


Laser Test Setup

Gate profiles validate cameras' temporal performance.

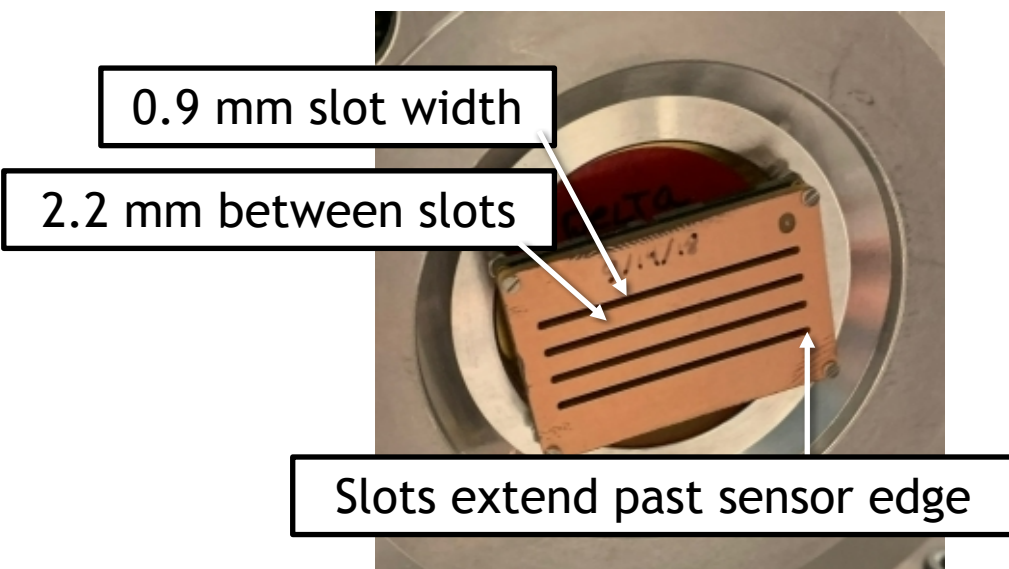


Slatfield testing shows that interframe crosstalk is relatively weak.

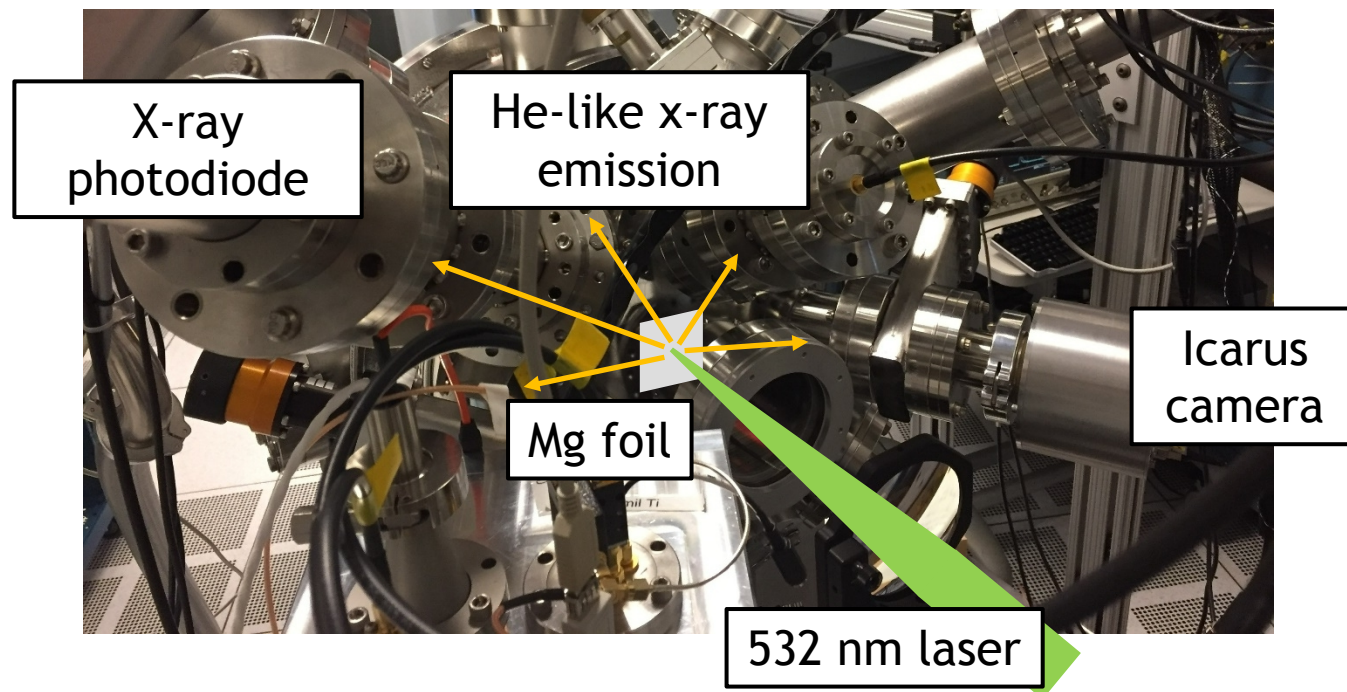
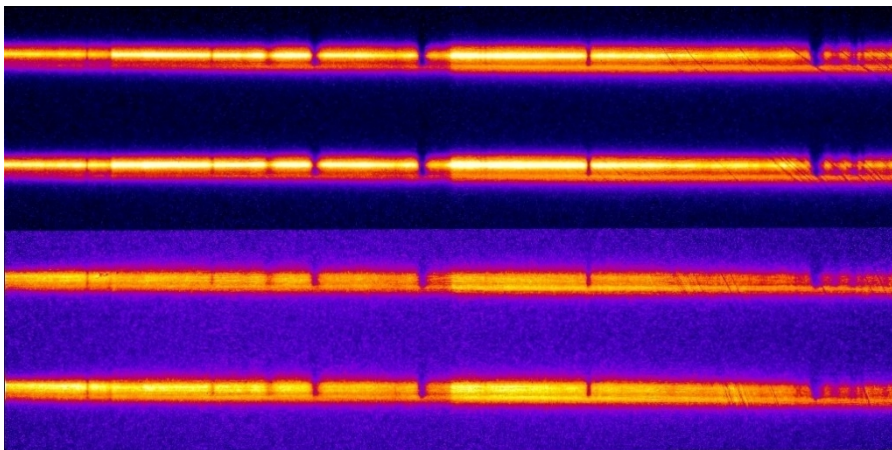


Crosstalk: Looker, Colombo, Kimmel, & Porter, *RSI* 91, 043502 (2020).
More on gate profiles: Hurd et al., *Proc. SPIE* 10763, 107630L (2018);
Hart et al., *Proc. SPIE* 11038, 110380Q (2019).

We fabricated a custom mask to replicate the opacity spectrometer's illumination pattern for high-fidelity testing.



2nd frame of Z3286



Chaco 1.35 keV pulsed source with “slatfield” mask



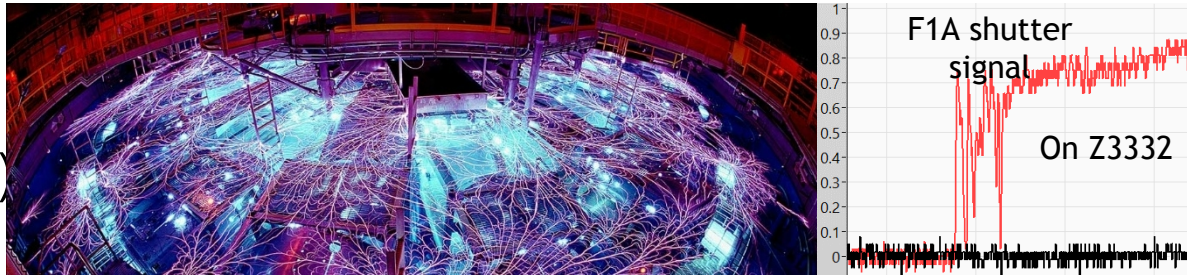
Z poses major environmental challenges: EMI, x-rays, shock, impact, debris, and soot.



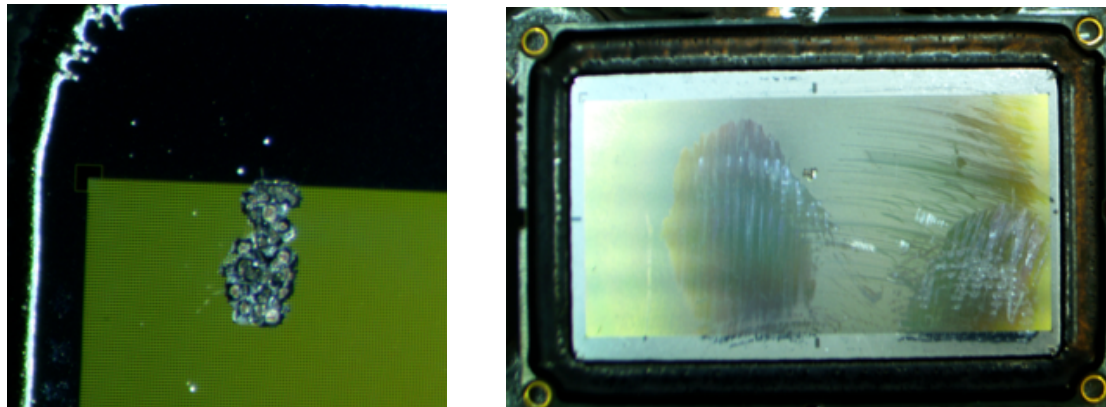
Types of challenges, ranked (approximately)

Best practices

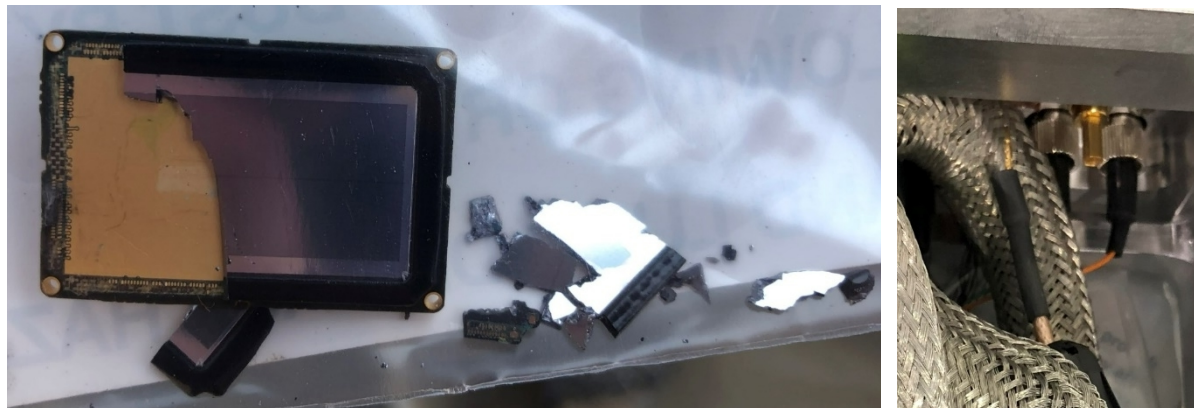
(1) EMI (& X-rays)



(2) Debris & Soot



(3) Shock & Impact



Isolate, regulate, buffer, multiply shield power line.
Sandwich PCB traces between ground planes.
Use fiber-optic data lines.
Alternate sets of insulating and conductive shielding layers.
Minimize number and size of camera body penetrations.

No line of sight from Z load to UXI if possible.
Mechanical protection in front of devices.
(At the cost of signal...)

Robust mounting for camera systems—
appropriately stiff or loose, depending on the
application.

Frame signals are recorded on capacitors under the detector layer.

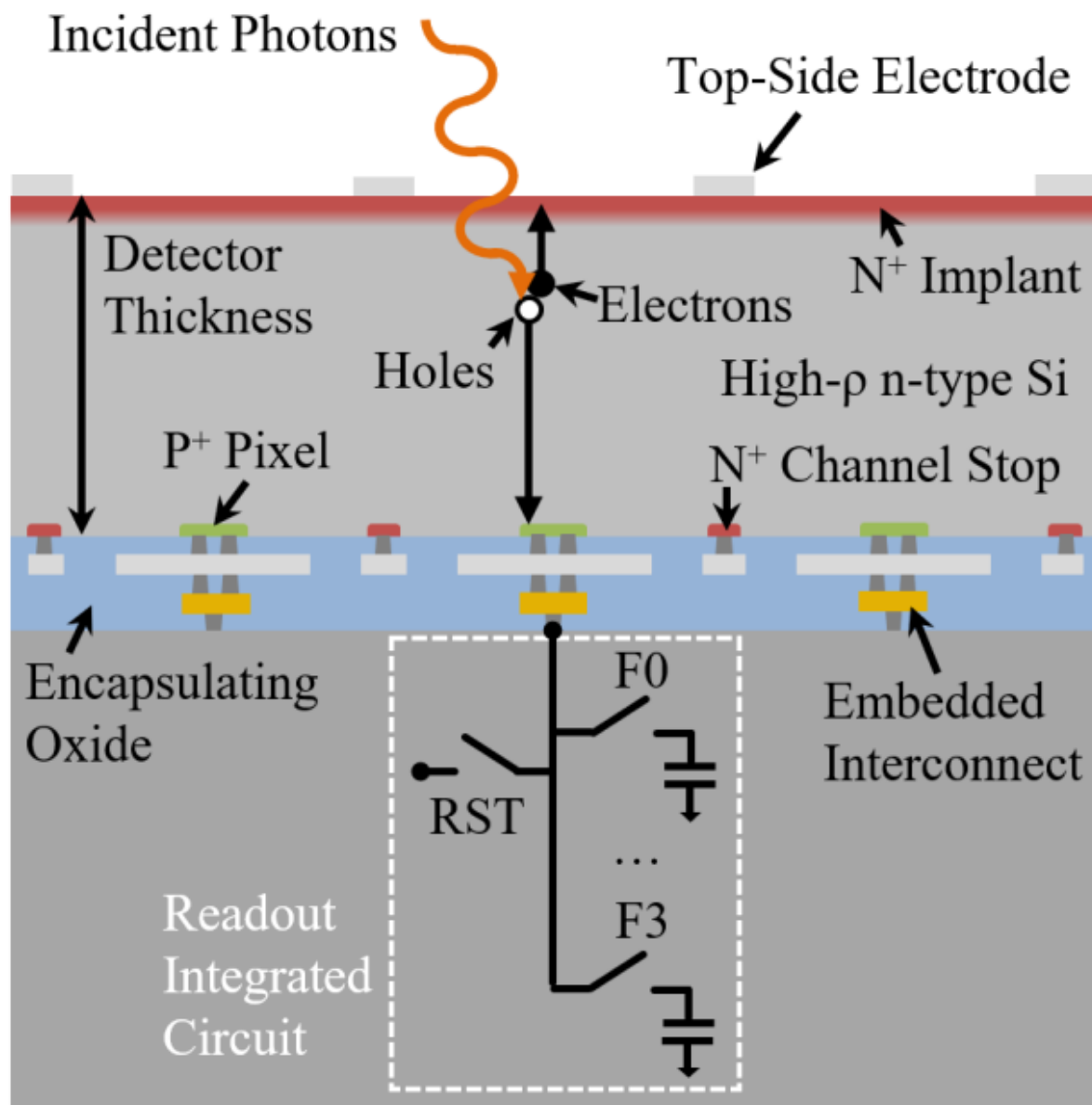


Fig. 1. Illustration of the Icarus sensor structure. A cross-section of the hybrid structure shows the Si detector layer (top) attached to the ROIC, with a schematic representation of the ROIC front end (bottom). The Si detector layer, with a physically defined thickness, generates a current pulse in response to illumination. The ROIC then samples the current with multiple integration frames according to a programmed timing pattern.